





15V NPN LOW SATURATION TRANSISTOR IN SOT23

Features

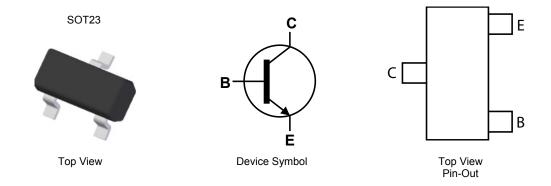
- BV_{CEO} > 15V
- I_C = 3A high Continuous Collector Current
- I_{CM} = 12A Peak Pulse Current
- R_{CE(sat)} = 50mΩ for a low equivalent On-Resistance
- 625mW Power dissipation
- hFE specified up to 12A for high current gain hold up
- Complementary PNP Type: FMMT717
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: molded plastic, "Green" molding compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ³
- Weight 0.008 grams (approximate)

Applications

- DC-DC / DC-AC Modules
- Regulator
- LED driver
- CCFL Backlighting Inverters



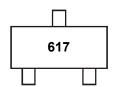
Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FMMT617TA	617	7	8	3,000
FMMT617TC	617	13	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



617 = Product Type Marking Code





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	15	V
Collector-Emitter Voltage	V _{CEO}	15	V
Emitter-Base Voltage	V_{EBO}	7	V
Continuous Collector Current	Ic	3	Α
Peak Pulse Current (Note 5)	I _{CM}	12	Α
Base Current	I _B	500	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	625	mW
Power Dissipation (Note 6)	P _D	806	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	200	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	155	°C/W
Thermal Resistance, Junction to Leads (Note 7)	R _{0JL}	194	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С

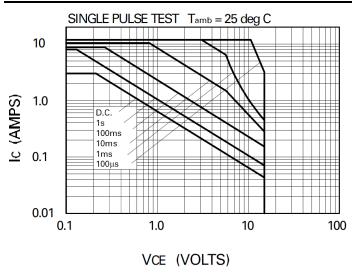
Notes:

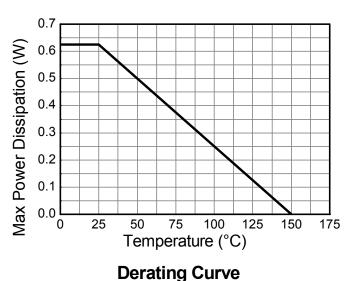
- 5. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 6. Same as note 5, except the device is measured at $t \le 5$ sec.
- 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
- 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



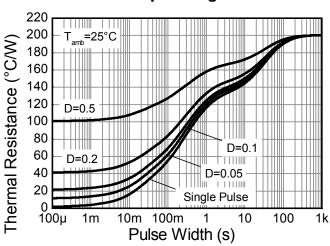


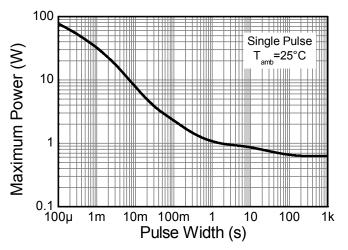
Thermal Characteristics and Derating information





Safe Operating Area





Transient Thermal Impedance

Pulse Power Dissipation





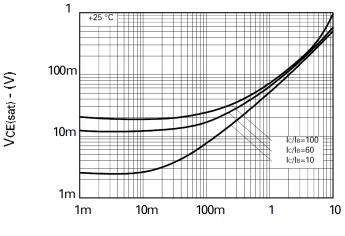
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	15	70	-	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	15	18	-	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV_{EBO}	7	8.2	-	V	I _E = 100μA
Collector Cut-off Current	I _{CBO}	-	<1	100	nA	V _{CB} = 10V
Emitter Cut-off Current	I _{EBO}	-	<1	100	nA	V _{EB} = 5.6V
Collector Emitter Cut-off Current	I _{CES}	-	<1	100	nA	V _{CES} = 10V
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	200 300 200 150	415 450 320 240 80		-	$\begin{split} &I_{C} = 10\text{mA}, \ V_{CE} = 2\text{V} \\ &I_{C} = 200\text{mA}, \ V_{CE} = 2\text{V} \\ &I_{C} = 3\text{A}, \ V_{CE} = 2\text{V} \\ &I_{C} = 5\text{A}, \ V_{CE} = 2\text{V} \\ &I_{C} = 12\text{A}, \ V_{CE} = 2\text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(sat)}	- - -	8 70 150	14 100 200	mV	$I_C = 0.1A$, $I_B = 10mA$ $I_C = 1A$, $I_B = 10mA$ $I_C = 3A$, $I_B = 50mA$
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	-	0.9	1.0	V	$I_C = 3A$, $I_B = 50mA$
Base-Emitter Saturation Voltage (Note 9)	$V_{BE(on)}$	-	0.84	1.0	V	$I_C = 3A, V_{CE} = 2V$
Transition Frequency	f _T	80	120	-	MHz	I _C = 50mA, V _{CE} = 10V, f = 50MHz
Collector Output Capacitance	C _{obo}	-	30	40	pF	V _{CB} = 10V, f = 1MHz
Turn-On Time	t _(on)	-	120	-	ns	V _{CC} = 10V, I _C = 3A,
Turn-Off Time	t _(off)	-	160	-	ns	$I_{B1} = -I_{B2} = 50 \text{mA}$

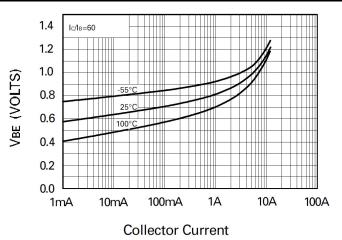
Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%



Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

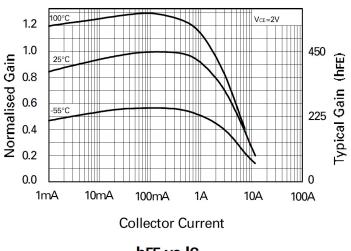


IC - Collector Current (A)

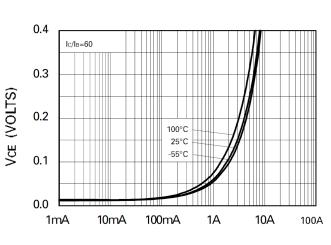


VBE(SAT) vs IC

VCE(SAT) v IC

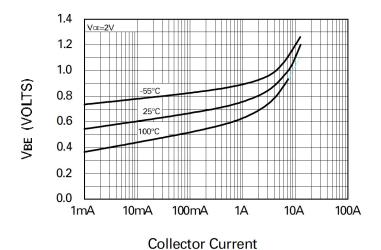


hFE vs IC



Collector Current

VCE(SAT) vs IC

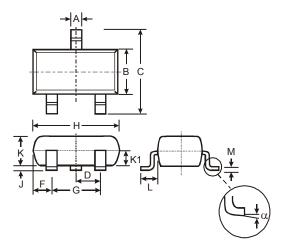






Package Outline Dimensions

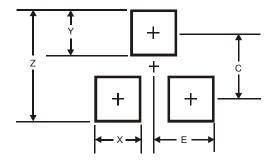
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.903	1.10	1.00			
K1	-	-	0.400			
L	0.45	0.61	0.55			
M	0.085	0.18	0.11			
α	0°	8°	-			
All	Dimens	ions in	mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
С	2.0
Ш	1.35





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SuperSOTSOT23 NPN SILICON POWER (SWITCHING) TRANSISTORS

625mW POWER DISSIPATION

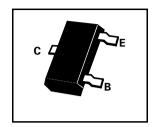
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SWITCHING) TRANSISTORS

* I_C CONT 3A

FFATURES

- * 12A Peak Pulse Current
- * Excellent H_{FF} Characteristics Up To 12A (pulsed)
- * Extremely Low Saturation Voltage E.g. 8mV Typ.
- * Extremely Low Equivalent On Resistance; R_{CE(sat)}



FMMT617 FMMT618

FMMT619 FMMT624

DEVICE TYPE	COMPLEMENT	PARTMARKING	R _{CE(sat)}
FMMT617	FMMT717	617	50m $Ω$ at 3 A
FMMT618	FMMT718	618	50m Ω at 2A
FMMT619	FMMT720	619	75m Ω at 2A
FMMT624	FMMT723	624	-
FMMT625	_	625	-

ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	FMMT 617	FMMT 618	FMMT 619	FMMT 624	FMMT 625	UNIT
Collector-Base Voltage	V _{CBO}	15	20	50	125	150	V
Collector-Emitter Voltage	V _{CEO}	15	20	50	125	150	V
Emitter-Base Voltage	V _{EBO}	5	5	5	5	5	V
Peak Pulse Current**	I _{CM}	12	6	6	3	3	Α
Continuous Collector Current	I _C	3	2.5	2	1	1	Α
Base Current	I _B	500					mA
Power Dissipation at T _{amb} =25°C*	Γ _{amb} =25°C* P _{tot} 625		mW				
Operating and Storage Temperature Range	T _j :T _{stg}	-55 to +150				°C	

Maximum power dissipation is calculated assuming that the device is mounted on a ceramic substrate measuring 15x15x0.6mm

^{**}Measured under pulsed conditions. Pulse width=300 μ s. Duty cycle \leq 2% Spice parameter data is available upon request for these devices

FMMT617

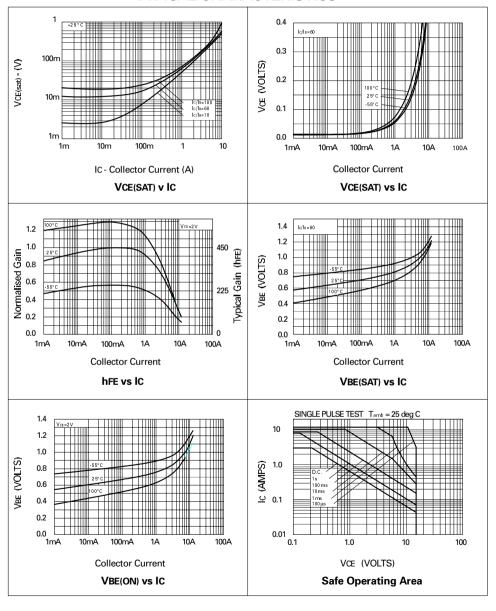
ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
Collector-Base Breakdown Voltage	V _{(BR)CBO}	15	70		V	I _C =100μA
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	15	18		V	I _C =10mA*
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	5	8.2		V	I _E =100μA
Collector Cut-Off Current	I _{CBO}			100	nA	V _{CB} =10V
Emitter Cut-Off Current	I _{EBO}			100	nA	V _{EB} =4V
Collector Emitter Cut-Off Current	I _{CES}			100	nA	V _{CES} =10V
Collector-Emitter Saturation Voltage	V _{CE(sat)}		8 70 150	14 100 200	mV mV mV	I _C =0.1A, I _B =10mA* I _C =1A, I _B =10mA* I _C =3A, I _B =50mA*
Base-Emitter Saturation Voltage	V _{BE(sat)}		0.9	1.0	V	I _C =3A, I _B =50mA*
Base-Emitter Turn-On Voltage	V _{BE(on)}		0.84	1.0	V	I _C =3A, V _{CE} =2V*
Static Forward Current Transfer Ratio	h _{FE}	200 300 200 150	415 450 320 240 80			I _C =10mA, V _{CE} =2V* I _C =200mA, V _{CE} =2V* I _C =3A, V _{CE} =2V* I _C =5A, V _{CE} =2V* I _C =12A, V _{CE} =2V*
Transition Frequency	f _T	80	120		MHz	I _C =50mA, V _{CE} =10V f=50MHz
Output Capacitance	C _{obo}		30	40	pF	V _{CB} =10V, f=1MHz
Turn-On Time	t _(on)		120		ns	V _{CC} =10V, I _C =3A
Turn-Off Time	t _(off)		160		ns	l _{B1} =l _{B2} =50mA

^{*}Measured under pulsed conditions. Pulse width=300µs. Duty cycle ≤ 2%

FMMT617

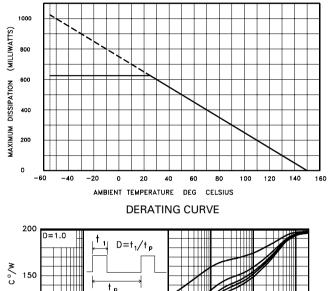
TYPICAL CHARACTERISTICS

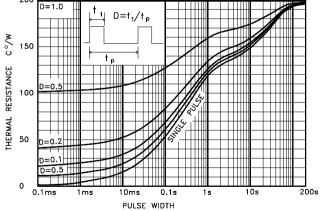


SuperSOT Series

FMMT717 FMMT722 FMMT718 FMMT723 FMMT720

THERMAL CHARACTERISTICS AND DERATING INFORMATION





MAXIMUM TRANSIENT THERMAL RESISTANCE

^{*} Reference above figures, Devices were mounted on a 15mmx15mm ceramic substrate